Ref #	Hits	Search Query	DBs	Default Operato r	Plural s	Time Stamp
L1	798531	wafer substrate	US-PGPU B; USPAT	OR	ON	2005/06/07 12:01
L2	3820	1 and ((bond\$3 near3 pad) and wir\$3 and (thin\$6 (reduc\$3 near3 thickness))and (solder near5 bump (bump near5 electrode)))	US-PGPU B; USPAT; USOCR	OR	ON	2005/06/07 12:01
L3	380	2 and (shim (support\$3 near10 metal))	US-PGPU B; USPAT; USOCR	OR	ON	2005/06/07 12:02
L4	162	3 and ring	US-PGPU B; USPAT; USOCR	OR	ON	2005/06/07 11:54
L5	1423406	wafer substrate	USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/07 12:01
L6	121	5 and ((bond\$3and pad) and wir\$3 and (thin\$6 (reduc\$3 and thickness))and (solder and bump (bump and electrode)))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/07 12:01
L7	3	6 and (shim (support\$3 and metal))	EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/06/07 12:02